


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MICROCONTROLLERS/24/14976	
<b>1.3 Title of PCN</b>	JSCC (China) LQFP7x7 48L , LQFP10x10 64L package copper palladium bonding wire introduction on STM32F2x, STM32F4x and STM32F7x listed products	
<b>1.4 Product Category</b>	STM32F20x / STM32F21x, STM32F40x / STM32F41x , STM32F42x / STM32F44x, STM32F72x / STM32F73x,	
<b>1.5 Issue date</b>	2024-12-04	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	PIKE EMMA
<b>2.1.2 Phone</b>	+44 1628896111
<b>2.1.3 Email</b>	emma.pike@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	StatsChipPAC JSCC Jiangyin (China)

**4. Description of change**

	Old	New
<b>4.1 Description</b>	Current Wire bonding material: - JSCC (China) Gold wire or Silver wire - AMKOR ATP (Philippines) gold wire - ASE Kaohsiung (Taiwan) Gold wire or Copper Palladium wire	Current Wire bonding material: - JSCC (China) Gold wire or Silver wire - AMKOR ATP (Philippines) gold wire - ASE Kaohsiung (Taiwan) Gold wire or Copper Palladium wire Added Wire bonding material : - JSCC (China) Copper Palladium wire
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	no impact on form, Fit, Function	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	To improve service
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	traceability ensured by ST Internal tools
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2025-02-03
<b>7.2 Intended start of delivery</b>	2025-02-03
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	14976 MDRF-GPM-RER2321 V5.0 - PCN14363 - PCN14922 - PCN14976 JSCC (China) LQ7 LQ10 and LQ12 CuPd - reliab report.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2024-12-04

**9. Attachments (additional documentations)**

14976 Public product.pdf  
14976 MDRF-GPM-RER2321 V5.0 - PCN14363 - PCN14922 - PCN14976 JSCC (China) LQ7 LQ10 and LQ12 CuPd - reliab report.pdf  
14976 \_Additional information.pdf

**10. Affected parts**

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F205RBT6	
	STM32F205RBT7	
	STM32F205RCT6	
	STM32F205RET6	
	STM32F205RET7	
	STM32F205RFT6	
	STM32F205RGT6	
	STM32F205RGT7	
	STM32F401RCT6	
	STM32F401RET6	
	STM32F405RGT6	
	STM32F405RGT7	
	STM32F410CBT3	
	STM32F411RET6	
	STM32F412RGT6	
	STM32F415RGT6	
	STM32F446RCT6	
	STM32F446RET6	
	STM32F722RET6	
	STM32F730R8T6	

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